L Number	Hits	Search Text	DB	Time stamp
1	0	semiconductor adj laser adj chip and resin and wavelength near6 "1.096"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:55
2	0	semiconductor adj laser adj chip and resin and wavelength near6 "1.069"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:56
3	0	semiconductor adj laser and wavelength near6 "1.069"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:56
4	505	semiconductor adj laser and carbon adj dioxide and wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:56
5	0	semiconductor adj laser and carbon adj dioxide and wavelength near6 ".mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:56
6	13	semiconductor adj laser and carbon adj dioxide and wavelength near6 micron	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:59
7	335	semiconductor adj laser and wavelength near6 micron	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 13:07
8	147	semiconductor adj laser.ti,ab,clm. and wavelength near6 micron	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 13:08
9	0	semiconductor adj laser.ti,ab,clm. and wavelength near6 micron and transparent near2 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 13:08
10	4	semiconductor adj laser.ti,ab,clm. and wavelength near6 micron and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 13:20
11	1	semiconductor adj laser.ti,ab,clm. and GaAs adj diode and resin and wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 14:21
12	5334	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.	USPAT; US-PGPUB	2004/06/20 14:26
13	39	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) and protect$3 and eye	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 14:31
14	5	(US-6654399-$ or US-5745515-$).did. or (US-20030035460-$ or US-20030035461-$ or US-20020154667-$).did.	USPAT; US-PGPUB	2004/06/20 14:31
15	0	((US-6654399-$ or US-5745515-$).did. or (US-20030035460-$ or US-20030035461-$ or US-20020154667-$).did.) and protect$3 near10 eye and diffus$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 14:32

16	0	((US-6654399-$ or US-5745515-$).did. or (US-20030035460-$ or US-20030035461-$ or US-20020154667-$).did.) and protect$3 near10 eye	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 14:32
17	597	(372/44).CCLS.	USPAT; US-PGPUB	2004/06/20 14:59
18	999	(372/43).CCLS.	USPAT; US-PGPUB	2004/06/20 14:59
19	877	((372/43).CCLS.) not ((372/44).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 15:00
20	11	(US-5422905-$ or US-5488678-$ or US-5373519-$ or US-5105237-$ or US-5907571-$ or US-5734672-$ or US-5758951-$ or US-6144684-$ or US-6654399-$).did. or (US-20030035460-$ or US-20030035461-$).did.	USPAT; US-PGPUB	2004/06/20 15:03
21	182	((372/29.01) or (372/29.014)).CCLS.	USPAT; US-PGPUB	2004/06/20 15:08
22	17	(((372/29.01) or (372/29.014)).CCLS.) and eye	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 15:08
23	2	(US-5383200-$ or US-5394419-$).did.	USPAT	2004/06/20 15:12
24	2	((US-5383200-$ or US-5394419-$).did.) and eye	USPAT	2004/06/20 15:12
-	2	("4829531").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/20 12:55
-	2	("4829531").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:31
-	2	("5488678").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:35
-	2	("5825952").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:33
-	0	jp-04449242$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:36
-	1	jp-04249442$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:39
-	0	jp-02511591$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:38
-	7	"511591"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 16:38

-	5296	(372/43).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	876	(372/44).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	3317	(372/45).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	2608	(372/46).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	122	(372/47).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	415	(372/48).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	601	(372/49).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	1634	(372/50).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:12
-	12010	((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:13
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and mold$2 near4 resin and diffusion adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:14
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or·((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and mold$2 near12 resin near12 diffusion near12 plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:15
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and mold$2 near12 resin near12 diffusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:16
-	8	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and mold$2 near12 resin and light near12 diffus$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 17:17
-	58	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and mold$2 near12 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 18:35

-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and spot adj size near12 resin near12 refractive adj index	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 18:36
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and spot adj size near12 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 18:36
-	1	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:14
-	305	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:16
-	305	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:23
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near4 ".mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:24
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 ".mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:24
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 $1".mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:25
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 "8.mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:26
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 "9.mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:26
-	0	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 "10.mu.m"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:27
-	43	(((372/43).CCLS.) or ((372/44).CCLS.) or ((372/45).CCLS.) or ((372/46).CCLS.) or ((372/47).CCLS.) or ((372/48).CCLS.) or ((372/49).CCLS.) or ((372/50).CCLS.)) and (beam adj size or beam adj diameter or spot adj size) near12 (larger or greater)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:29

-		4	"6111283"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 13:42
-		2	("5502320").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 13:42
-		2	("5986304").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 13:43
-		2	("6111283").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 13:43
-		173	laser.ti. and 372/43.ccls. and (mqw or multiple adj quantum adj well)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 14:29
-		33	laser.ti. and 372/43.ccls. and (mqw or multiple adj quantum adj well) and high adj power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 14:29
-		0	laser.ti. and 372/43.ccls. and (mqw or multiple adj quantum adj well) and high adj power near12 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 14:30
-		3	laser.ti. and 372/43.ccls. and (mqw or multiple adj quantum adj well) and high adj power and spot adj size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 15:22
-		6	laser.ti. and 372/43.ccls. and ((second or additional or plurality) adj laser adj (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:26
-		0	laser.ti. and 372/43.ccls. and molded adj resin near15 epoxy near15 silica	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:28
-		1	laser.ti. and 372/43.ccls. and epoxy near15 silica near15 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:28
-		1	laser.ti. and 372/43.ccls. and epoxy same silica same resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:29
-		0	laser.ti. and 372/43.ccls. and resin near15 mixture near15 (silica or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:30
-		1	372/43.ccls. and resin near15 mixture near15 (silica or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:32

-	2742	resin near6 silica near6 epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:34
-	6327	molded adj resin near (resin near6 silica near6 epoxy) epoxy near15 silica	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:34
-	109	molded adj resin near (resin near6 silica near6 epoxy) epoxy near15 silica and laser.ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 16:34
-	7	molded adj resin near (resin near6 silica near6 epoxy) (mixture or mixed) near15 epoxy near15 silica and laser.ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 17:38
-	7	(seal or molded) adj resin near (resin near6 silica near6 epoxy) (mixture or mixed) near15 epoxy near15 silica and laser.ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 17:39
-	29	(seal or molded) near3 resin near (resin near6 silica near6 epoxy) (mixture or mixed) near15 epoxy near15 silica and laser.ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:08
-	20	jp-0818163$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:09
-	0	jp-0818163$-$.did. and double adj sealing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:09
-	116	double adj sealing and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:09
-	23	double adj sealing near12 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:24
-	1977	(mixing or mix or mixture) near12 resin and (light adj emitting or light-emitting or laser).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 18:26
-	14	(mixing or mix or mixture) near12 resin near12 refractive adj index and (light adj emitting or light-emitting or laser).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 19:06
-	19	(thermal adj resistance or heat adj capacity) near15 (chip or die) and laser.ti,ab,clm. and (372/$6.ccls. or 257/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 19:22
-	0	(thermal adj resistance or heat adj capacity) near15 (chip or die) and heat adj sink near15 (contain or container) and laser.ti,ab,clm. and (372/$6.ccls. or 257/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 19:24

-	0	(thermal adj resistance or heat adj capacity) near15 (chip or die) and heat adj sink near15 (contain or container) and laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 19:24
-	26	(thermal adj resistance or heat adj capacity) near15 (chip or die) and heat adj sink near15 (contain or container)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 19:25
-	170	(372/4$1.ccls. or 372/50.ccls.) and thermal adj resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:34
-	2	(372/4$1.ccls. or 372/50.ccls.) and (thermal adj resistance near15 "deg/W")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:37
-	2	(372/4$1.ccls. or 372/50.ccls.) and "deg/W"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:37
-	2	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and "deg/W"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:40
-	3654	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ("deg/W" or (thermal resistance near12 heat sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:41
-	2868	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ("deg/W" or (thermal resistance near12 heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:42
-	2867	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ("deg/W" or (thermal resistance near6 heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:43
-	365	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ("deg/W" or (low near6 thermal resistance near6 heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:43
-	2	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ("deg/W" or (low near6 thermal near6 resistance near6 heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:44
-	1	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and ((low or lower) near6 thermal near6 resistance near6 heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:46

-	19	(372/4$1.ccls. or 372/50.ccls. or 257/79.ccls. or 257/8$1.ccls. or 257/9$1.ccls. or 257/100.ccls. or 257/101.ccls. or 257/102.ccls. or 257/103.ccls.) and (thermal adj resistance near6 heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 10:49
-	1	thermal adj resistance near3 copper near12 "deg/W"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:17
-	9	(thickness or thick) near4 heat adj sink and (257/$6.ccls. or 372/$6.ccls.) and (area near4 bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 11:19
-	25	(US-5307362-$ or US-5373519-$ or US-5422905-$ or US-6448583-$ or US-6049423-$ or US-5105237-$ or US-5970081-$ or US-5734672-$ or US-6219364-$ or US-6049125-$ or US-5758951-$ or US-6133631-$ or US-6144684-$ or US-4829531-$ or US-5488678-$ or US-5825952-$ or US-5907571-$ or US-5355385-$).did. or (DE-4315581-$).did. or (JP-61176169-$ or JP-05129730-$).did. or (EP-257898-$ or JP-07045811-$ or JP-09127349-$ or EP-483549-$).did.	USPAT; EPO; JPO; DERWENT	2002/11/02 11:53
-	0	heat adj sink near12 "W/deg" and (laser or light-emtting or light adj emitting).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:18
-	0	heat adj sink near12 "W/deg" and (laser or light-emitting or light adj emitting).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:18
-	0	heat adj sink near12 "W/deg" and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:19
-	193	heat adj sink near12 thermal adj resistance and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:20
-	43	heat adj sink near12 thermal adj resistance near12 low and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:36
-	1	heat adj sink near12 thermal adj resistance near12 low near12 (copper or cu) and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:22
-	43	heat adj sink near12 thermal adj resistance near12 low and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:23
-	0	heat adj sink near12 thermal adj resistance near12 low near12 "K/W" and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:37

-		0	heat adj sink near12 thermal adj resistance near12 "K/W" and (257/$6.ccls. or 438/$6.ccls. or 372/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:38
-		0	heat adj sink near12 (copper or cu) near12 thermal adj resistance near12 "K/W"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 12:39
-		27	(US-5825952-$ or US-6049125-$ or US-6219364-$ or US-6448583-$ or US-5422905-$ or US-5970081-$ or US-5734672-$ or US-6144684-$ or US-6133631-$ or US-5758951-$ or US-6049423-$ or US-4829531-$ or US-5488678-$ or US-4899210-$ or US-5373519-$ or US-5307362-$ or US-5105237-$ or US-5907571-$ or US-5355385-$ or US-5381859-$).did. or (DE-4315581-$).did. or (JP-61176169-$ or JP-05129730-$).did. or (JP-09127349-$ or EP-257898-$ or JP-07045811-$ or EP-483549-$).did.	USPAT; EPO; JPO; DERWENT	2002/11/02 13:46
-		2	monochromatic near12 laser adj diode adj array	USPAT; EPO; JPO; DERWENT	2002/11/02 13:47
-		5	laser adj diode adj array near12 "same wavelength"	USPAT; EPO; JPO; DERWENT	2002/11/02 17:01
-		4	(mqw or multiple adj quantum adj well) near6 different adj wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 18:59
-		2	("6049125").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 19:32
-		2	("6049423").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 19:37
-		14	(("6049423") or ("6049125") or ("5625402") or ("5422905") or ("5970081") or ("5355385") or ("5907571")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/02 19:37
-		7	(("6049423") or ("6049125") or ("5625402") or ("5422905") or ("5970081") or ("5355385") or ("5907571")).PN.	USPAT	2002/11/02 19:38
-		2	semiconductor.ti,ab,clm. and laser.ti,ab,clm. and resin near12 (mixture or mix or mixing or mixed) near12 diffusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 16:03
-		6	laser.ti,ab,clm. and resin near12 (mixture or mix or mixing or mixed) near12 diffusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 16:07
-		3	laser.ti,ab,clm. and (light-diffusing or light adj diffusing) near3 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 16:08

–	6	laser.ti,ab,clm. and (light-diffusing or light adj diffusing) near5 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 16:09
–	34	(US-5614338-$ or US-5530780-$ or US-5976175-$ or US-5307362-$ or US-5355385-$ or US-5105237-$ or US-5373519-$ or US-5970081-$ or US-6133631-$ or US-6144684-$ or US-5734672-$ or US-6448583-$ or US-5422905-$ or US-4899210-$ or US-5625402-$ or US-5758951-$ or US-6219364-$ or US-6049423-$ or US-5488678-$ or US-5825952-$ or US-4829531-$ or US-5907571-$ or US-6049125-$ or US-5381859-$).did. or (US-20030031917-$).did. or (DE-4315581-$).did. or (JP-04037487-$ or JP-61176169-$ or JP-05129730-$).did. or (GB-2142441-$ or JP-07045811-$ or JP-09127349-$ or EP-257898-$ or EP-483549-$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 17:38
–	18	(diffuse or diffusive) near12 resin and laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:01
–	0	eye near12 protect$3 and laser.ti,ab,clm. and resin near12 diffus$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:03
–	0	eye near12 protect$3 and laser.ti,ab,clm. and resin near12 (light-diffus$3 or diffus$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:03
–	156	laser.ti,ab,clm. and resin near12 (light-diffus$3 or diffus$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:03
–	4	laser.ti,ab,clm. and resin near12 light-diffus$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:13
–	34	laser.ti,ab,clm. and resin near12 (light near5 diffus$3 or light-diffus$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:21
–	115	semiconductor adj laser.ti,ab,clm. and resin near6 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:25
–	62	semiconductor adj laser.ti,ab,clm. and resin near3 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:25
–	0	semiconductor adj laser.ti,ab,clm. and light-diffus$3 near6 resin near3 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:26
–	1	semiconductor adj laser.ti,ab,clm. and (light near3 diffus$3 or light-diffus$3) near6 resin near6 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:28
–	1	semiconductor adj laser.ti,ab,clm. and (light near6 diffus$3 or light-diffus$3) near12 resin near6 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:29
–	1	semiconductor.ti,ab,clm. and laser.ti,ab,clm. and (light near6 diffus$3 or light-diffus$3) near12 resin near6 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:34

-	3	semiconductor.ti,ab,clm. and (light-emitting laser).ti,ab,clm. and (light near6 diffus$3 or light-diffus$3) near12 resin near6 lens	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/13 18:34
-	126	resin near6 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:18
-	66	resin near3 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:21
-	0	light-diffusive near6 resin near3 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:19
-	0	(light near6 (diffusive or diffusion or diffuse) or light-diffusive) near6 resin near3 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:20
-	0	(light near12 (diffusive or diffusion or diffuse) or light-diffusive) near12 resin near12 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:21
-	34	resin near2 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:22
-	0	molded near2 resin near2 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:22
-	7	molded near12 resin near2 lens and semiconductor adj2 laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:28
-	2	laser.ti,ab,clm. and light-diffusive near6 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 10:30
-	16	laser.ti,ab,clm. and (light near3 (diffusive or diffusion or diffuse) light-diffusive) near6 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:40
-	1	jp-07072311$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:41
-	2	("5976175").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:56
-	0	("761240.ap.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:56

-	4	761240.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:56
-	11	"5177753"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/18 17:38
-	2	("5177753").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/18 17:38
-	4	667775.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 16:50
-	2	("5386428").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 17:26
-	2	("5970081").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:21
-	2	("5422905").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:43
-	2	("4870652").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:45
-	0	("dualnear2lasernear2beamssamewavelength").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:45
-	14	dual near2 laser near2 beams same wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:57
-	0	multiple adj beam adj semiconductor adj laser and "same wavelengths"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:58
-	19	multiple adj beam adj semiconductor adj laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 18:58
-	6	multiple adj beam adj semiconductor adj laser and wavelengths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 19:46
-	0	multiple adj beam adj semiconductor adj laser and different adj wavelengths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 19:47

-	12	multiple adj beam adj semiconductor adj laser and (wavelength wavelengths frequency frequencies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:23
-	6	(("4745294") or ("4768081") or ("5052005")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:23
-	0	((("4745294") or ("4768081") or ("5052005")).PN.) and (wavelength frequency wavelengths frequencies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:24
-	2233	semiconductor adj laser.ti,ab,clm. and wavelength near3 range	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:25
-	1117	semiconductor adj laser.ti,ab,clm. and wavelength near3 range.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:26
-	376	semiconductor adj laser.ti. and wavelength near3 range.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:26
-	1	semiconductor adj laser.ti. and wavelength near3 range.clm. and resin and encapsulat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:27
-	0	semiconductor adj laser.ti. and wavelength near6 ".mu.m" and resin and encapsulat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:28
-	0	semiconductor adj laser.ti. and wavelength near6 (micron micrometer ".mu.m") and resin and encapsulat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:28
-	1	semiconductor adj laser.ti. and wavelength near6 (micron micrometer ".mu.m") and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/19 20:28